

1 Substrate: 3.18mm ±0.18mm [0.125" ±0.007"] per IPC 4101/21, silver surface finish.


2 Solder ball: SAC305 alloy

**RoHS COMPLIANT**

Description: **BGA Surface Mount Adaptor**

400 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

|   |                            |                  |                |        |
|---|----------------------------|------------------|----------------|--------|
| <b>SF-BGA400F-B-05F Drawing</b>   |                            | Status: Released | Scale: 3:1     | Rev: A |
|  <p>© 2002 IRONWOOD ELECTRONICS, INC.<br/>PO BOX 21151 ST. PAUL, MN 55121<br/>Tele: (651) 452-8100<br/>www.ironwoodelectronics.com</p> | Drawing: H. Hansen         |                  | Date: 12/14/05 |        |
|   | File: SF-BGA400F-B-05F Dwg |                  | Modified:      |        |